

MATERIAL DECLARATION SHEET



Material number	SSD-1000A-C			
Product Line	Current Sensor			
Compliance Date	5/8/2025			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material/	CASRN	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
				Substances	if applicable			
1	Ceramic Capacitor 10UF 16V	Dielectric	0.002	Barium Titanate (IV)	12047-27-7	96.700	0.002	0.002
				Additives	Trade Secret	3.300	0.0001	
		Inner Electrode	0.001	Nickel	7440-02-0	100.000	0.001	0.001
		Terminal Electrode	3.09	Copper	7440-50-8	100.000	2.141	2.14
		Electro-Plating	0.0004	Nickel	7440-02-0	62.500	0.0002	0.0003
				Tin	7440-31-5	37.500	0.0001	
2	Capacitor 0.1uF 25V X7R x8	Ceramic Substrate	0.04	Barium Titanate (IV)	12047-27-7	100.000	0.028	0.03
		Inner electrode	0.0007	Nickel	7440-02-0	100.000	0.001	0.001
		Termination electrode	0.005	Copper	7440-50-8	100.000	0.004	0.004
		Under plating	0.0001	Nickel	7440-02-0	100.000	0.0001	0.0001
		Surface plating	0.0005	Tin	7440-31-5	100.000	0.0003	0.0003
3	Capacitor 22uF 10V X7T x2	Ceramic Element	0.03	Barium oxide	1304-28-5	60.000	0.013	0.02
				Titanium Oxide	13463-67-7	30.000	0.007	
				Misc.	Trade Secret	10.000	0.002	

MATERIAL DECLARATION SHEET



		Nickel Plating Layer	0.0002	Nickel	7440-02-0	100.000	0.0002	0.0002
		Inner Electrode	0.01	Nickel	7440-02-0	100.000	0.005	0.005
		Tin Plating Layer	0.001	Tin	7440-31-5	100.000	0.000	0.000
		Outer electrode	0.006	Copper	7440-50-8	90.000	0.004	0.004
Diboron trioxide	1303-86-2			2.000	0.0001			
Silicon dioxide	7631-86-9			8.000	0.0003			
4	Resistor 47 OHM 1% 1/10W	Ceramic	0.002	Aluminum oxide	1344-28-1	96.000	0.001	0.002
				Silicon dioxide	14808-60-7	2.000	0.00003	
				Magnesium oxide	1309-48-4	2.000	0.00003	
		Inner Electrode C1	0.00002	Silver	7440-22-4	98.500	0.00001	0.00001
				Palladium	7440-05-3	1.500	0.0000002	
		Inner Electrode C2	0.00001	Silver	7440-22-4	100.000	0.00001	0.00001
				Resistive layer	0.00002	Silver	7440-22-4	
		Ruthenium(IV) oxide	12036-10-1			72.000	0.00001	
		Lead bisilicate	65997-18-4			18.000	0.000002	
		Termination	0.0002	Nickel	7440-02-0	65.660	0.0001	0.0001
				Tin	7440-31-5	34.340	0.00004	
		Primary glass	0.00002	Glass wool	65997-17-3	100.000	0.00001	0.00001
Overcoat II	0.00003	Bisphenol A epoxy resin	25068-38-6	100.000	0.00002	0.00002		
Marking	0.0000003	Bisphenol A epoxy resin	25068-38-6	100.000	0.0000002	0.0000002		
5	Ceramic Capacitor 0.22UF	Dielectric	0.0037	Barium Titanate (IV)	12047-27-7	97.820	0.002	0.003
				Additives	Trade Secret	2.180	0.0001	
		Inner Electrode	0.0005	Nickel	7440-02-0	100.000	0.0003	0.0003
		Terminal Electrode	0.0009	Copper	7440-50-8	100.000	0.001	0.001
		Electro-Plating	0.0001	Nickel	7440-02-0	63.640	0.0000	0.0001
				Tin	7440-31-5	36.360	0.00003	
6		Inner Electrode	0.0005	Nickel	7440-02-0	48.700	0.0002	0.0003

MATERIAL DECLARATION SHEET



	Resistors SMD 200 OHM 0.1% x2		0.0018	Copper	7440-50-8	49.390	0.0002	0.0012
				Tin	7440-31-5	1.910	0.000006	
		Protective Film	0.0018	Silicon Dioxide	7631-86-9	66.000	0.0008	0.0012
				Misc. not to declare	Propietary	34.000	0.0004	
		External Electrode	0.0003	Tin	7440-31-5	100.000	0.0002	0.0002
		Ceramic	0.0072	Aluminum Oxide	1344-28-1	99.500	0.0050	0.0050
				Silicon Dioxide	14808-60-7	0.300	0.00002	
				Magnesium Oxide	1309-48-4	0.200	0.00001	
		Resistive element	0.000001	Nickel	7440-02-0	50.000	0.0000004	0.0000008
				Chromium	7440-47-3	50.000	0.0000004	
		Marking	0.00003	Silicon Dioxide	7631-86-9	100.000	0.00002	0.00002
7	TVS Diode 60VWM 96.8VC	Dice	0.001	Silicon	7440-21-3	60.180	0.001	0.001
				Phosphorus	7723-14-0	0.010	0.0000001	
				Boron	7440-42-8	0.010	0.0000001	
				Nickel	7440-02-0	14.800	0.0001	
				Lead	7439-92-1	12.500	0.0001	
				Silicon Dioxide	7631-86-9	10.000	0.0001	
				Aluminum Oxide	1344-28-1	2.500	0.00002	
		Solder paste	0.002	Tin	7440-31-5	5.000	0.00007	0.001
				Lead	7439-92-1	92.500	0.001	
				Silver	7440-22-4	2.500	0.00003	
		Lead frame	0.03	Copper	7440-50-8	99.800	0.019	0.02
				Iron	7439-89-6	0.150	0.00003	
				Phosphorus	7723-14-0	0.050	0.00001	
		Epoxy	0.031	Silicon dioxide	14808-60-7	76.000	0.02	0.02
				Epoxy resin	25928-94-3	9.000	0.002	
				Phenolic resin-A,B	9003-35-4	8.000	0.002	
				Hydroxide metal	Trade Secret	6.000	0.001	
				Carbon black	1333-86-4	1.000	0.0002	
		Plating	0.0007	Tin	7440-315	100.000	0.0005	0.0005

MATERIAL DECLARATION SHEET



8	Voltage Regulator Non-Isolated	Ferrite Core	0.024	Iron Oxide	1332-37-2	65.000	0.01	0.02
				Copper oxide	1317-38-0	4.200	0.001	
				Nickel monoxide	1313-99-1	8.800	0.001	
				Zinc Oxide	1314-13-2	22.000	0.004	
		Epoxy	0.005	Bisphenol A epoxy resin	25068-38-6	100.000	0.003	0.003
		Terminal	0.0003	Silver	7440-22-4	100.000	0.0002	0.0002
		Plating	0.0005	Nickel	7440-02-0	33.000	0.0001	0.0004
				Tin	7440-31-5	67.000	0.0003	
		Ceramics/Glass	0.0018	Silicon	7440-21-3	100.000	0.001	0.001
		Wire	0.007	Polyurethane Foam	9009-54-5	4.000	0.0002	0.00
				Copper	7440-50-8	96.000	0.005	
		Marking	0.000001	Cellulose nitrate	9004-70-0	100.000	0.000001	0.000001
		Solder paste	0.001	Ethoxylated tallow amine	61791-26-2	3.900	0.00003	0.001
				Di-carboxylic acids	68937-72-4	2.750	0.00002	
				Alpha-terpineol	98-55-5	3.500	0.00002	
				Copper Powder	7440-22-4	3.200	0.00002	
				Zinc	7440-31-5	86.650	0.001	
		Plating	0.0035	Copper	7440-50-8	100.000	0.002	0.002
		Solder Mask	0.00035	Modified epoxy resin	Propietary	37.000	0.0001	0.0002
				Organic substance	Propietary	6.000	0.00001	
				Barium sulphate	7727-43-7	14.000	0.00003	
				1-Butanol,3-methoxy-3-methyl-,acetate)	Propietary	15.000	0.00004	
				Solvent naphtha(heavy arom)	Propietary	5.000	0.00001	
				Talc	14807-96-6	13.000	0.00003	
				Silicon ,vitreous	trade secret	10.000	0.00002	
		Prepreg	1.556	Silicon Dioxide	7631-86-9	50.000	0.54	1.08
				Glass, oxide, chemicals	65997-17-3	39.000	0.42	
				Epoxy resin A	Propietary	7.000	0.08	
				Cyanate Resin	Propietary	3.000	0.032	
				Epoxy resin B	Propietary	1.000	0.011	

MATERIAL DECLARATION SHEET



		ABF	0.0011	Silicon Dioxide	7631-86-9	62.460	0.0005	0.001
				Bisphenol A epoxy resin	25068-38-6	3.930	0.00003	
				Others, not to declare	Trade Secret	33.610	0.00025	
9	Capacitor CER 0.033UF	Dielectric	0.010	Barium Titanate (IV)	12047-27-7	3.580	0.0002	0.007
				Calcium zirconate	12013-47-7	93.350	0.006	
				Other, not to declare	Trade Secret	3.070	0.0002	
		Inner Electrode	0.003	Strontium oxide	1314-11-0	53.690	0.0013	0.002
				Nickel	7440-02-0	46.310	0.0011	
		Electro-plating	0.0003	Nickel	7440-02-0	38.000	0.0001	0.0002
				Tin	7440-31-5	62.000	0.0001	
		Terminal Electrode	0.0022	Copper	7440-50-8	100.000	0.0015	0.002
10	Connector R/A 2POS 0.38um GOLD 2	LCP-GF30	0.21	Carbon Black	1333-86-4	0.500	0.001	0.145
				Liquid Crystal Polymer	70679-92-4	68.000	0.1	
				Further Additives	Trade Secret	1.500	0.002	
				Glass Fiber	65997-17-3	30.000	0.044	
		Tin Plating	0.002	Tin	7440-31-5	100.000	0.001	0.001
		Gold Plating	0.0002	Cobalt	7440-48-4	0.250	0.0000004	0.0001
				Nickel	7440-02-0	0.250	0.0000004	
				Gold	7440-57-5	99.500	0.0001	
		Nickel Plating	0.003	Nickel	7440-02-0	100.000	0.002	0.002
		Cartridge Brass 70% Unplate	0.086	Copper	7440-50-8	70.000	0.042	0.06
				Nickel	7440-02-0	30.000	0.018	
11	Connector R/A 4POS 0.38um GOLD x2	LCP-GF30	0.7	Carbon Black	1333-86-4	0.500	0.002	0.471
				Liquid Crystal Polymer	70679-92-4	68.000	0.320	
				Further Additives	Trade Secret	1.500	0.007	
				Glass Fiber	65997-17-3	30.000	0.141	
		Tin Plating	0.007	Tin	7440-31-5	100.000	0.005	0.005

MATERIAL DECLARATION SHEET



		Gold Plating	0.0008	Cobalt	7440-48-4	99.500	0.001	0.001		
				Nickel	7440-02-0	0.250	0.000001			
				Gold	7440-57-5	0.250	0.000001			
		Nickel Plating	0.01	Nickel	7440-02-0	100.000	0.009	0.009		
		Cartridge Brass 70% Unplate	0.344	Copper	7440-50-8	70.000	0.167	0.238		
Nickel	7440-02-0			30.000	0.071					
12	Analog Front End IC	Bond Wire	0.00006	Copper	7440-50-8	97.534	0.00004	0.00004		
				Proprietary materials		Trade Secret	0.011		0.000000005	
				Gold	7440-57-5	0.052	0.00000002			
				Palladium	7440-05-3	2.400	0.000001			
				Silver	7440-22-4	0.003	0.000000001			
		Die Attach Adhesive	0.00068	Silver	7440-22-4	80.000	0.0004	0.0005		
				Epoxy	85954-11-6	20.000	0.0001			
		Lead Frame	0.0286	Copper	7440-50-8	97.585	0.02	0.02		
				Iron	7439-89-6	2.300	0.0005			
				Phosphorus	7723-14-0	0.015	0.000003			
				Zinc	7440-66-6	0.100	0.00002			
		Lead Frame Plating	0.0001	Nickel	7440-02-0	95.120	0.0001	0.0001		
				Gold	7440-57-5	0.780	0.000001			
				Palladium	7440-05-3	4.100	0.000003			
		Mold Compound	0.046	Silicon Dioxide	60676-86-0	86.000	0.03	0.03		
				Carbon Black	1333-86-4	0.300	0.0001			
				Epoxy	85954-11-6	13.700	0.004			
		Semiconductor	0.002	Silicon	7440-21-3	100.000	0.002	0.002		
		13	Voltage Regulators IC	Bond Wire	0.00002	Gold	7440-57-5	100.000	0.00002	0.000016
				Die Attach Adhesive	0.00029	Silver	7440-22-4	80.000	0.0002	0.0002
Epoxy	85954-11-6					20.000	0.00004			
Lead Frame	0.006			Copper	7440-50-8	97.420	0.0044	0.0045		
				Iron	7439-89-6	2.380	0.0001			
				Phosphorus	7723-14-0	0.080	0.000004			

MATERIAL DECLARATION SHEET



		Lead Frame Plating	0.0001	Zinc	7440-66-6	0.120	0.00001	0.0001
				Nickel	7440-02-0	95.120	0.0001	
				Gold	7440-57-5	0.780	0.000001	
				Palladium	7440-05-3	4.100	0.000003	
		Mold Compound	0.011	Silicon Dioxide	60676-86-0	86.000	0.0064	0.007400
				Carbon Black	1333-86-4	0.500	0.00004	
				Epoxy	85954-11-6	13.500	0.0010	
		Semiconductor	0.0009	Silicon	7440-21-3	100.000	0.001	0.0006029
14	Ceramic Capacitor 1UF 25V X7R x4	Dielectric	0.015	Barium Titanate (IV)	12047-27-7	100.000	0.010	0.010
		Inner electrode	0.009	Nickel	7440-02-0	100.000	0.006	0.006
		First Layer	0.0007	Copper	7440-50-8	100.000	0.000	0.000
		Second Layer	0.0007	Nickel	7440-02-0	100.000	0.0005	0.0005
		Third Layer	0.0006	Tin	7440-31-5	100.000	0.0004	0.0004
15	Microcontroller IC	Mold Compound	0.23	Silica, Vitreous	60676-86-0	86.910	0.14	0.16
				Epoxy Resin	Trade Secret	7.670	0.01	
				Phenolic Resin	Trade Secret	5.110	0.01	
				Carbon Black	1333-86-4	0.310	0.000	
		Die Attach	0.002	Silver	7440-22-4	75.000	0.001	0.001
				Modified Epoxy Resin	13561-08-5	14.000	0.0002	
				Diglycidylether of Bisphenol-F	54208-63-8	7.500	0.0001	
				Modified Amine	827-43-0	3.500	0.0001	
		Lead Frame	0.030	Copper	7440-50-8	95.540	0.02	0.02
				Iron	7439-89-6	2.350	0.000	
				Silver	7440-22-4	1.900	0.0004	
				Zinc	7440-66-6	0.130	0.0000	
				Phosphorous	7723-14-0	0.080	0.00002	
		Chip (Die)	0.022	Doped Silicon	7440-21-3	100.000	0.01	0.01
		Bond Wire	0.001	Doped Gold	7440-57-5	100.000	0.0004	0.0004
		Plating	0.004	Tin	7440-31-5	100.000	0.002	0.002

MATERIAL DECLARATION SHEET



16	CAN transceiver	Bond Wire	0.00002	Calcium	7440-70-2	0.001	0.0000000001	0.00002
				Yttrium	7440-65-5	0.001	0.0000000001	
				Gold	7440-57-5	99.998	0.0000000001	
				Silver	7440-22-4	0.001	0.00002	
		Die Attach Adhesive	0.0007	Silver	7440-22-4	75.000	0.0004	0.001
				Epoxy	85954-11-6	25.000	0.0001	
		Die Attach Adhesive 2	0.0001	Silver	7440-22-4	75.000	0.0001	0.0001
				Epoxy	85954-11-6	25.000	0.00002	
		Die Attach Adhesive 3	0.0001	Silver	7440-22-4	75.000	0.0001	0.0001
				Epoxy	85954-11-6	25.000	0.00002	
		Lead Frame	0.18	Copper	7440-50-8	97.050	0.12	0.124
				Iron	7439-89-6	2.600	0.003	
				Phosphorus	7723-14-0	0.150	0.0002	
				Zinc	7440-66-6	0.200	0.0002	
		Lead Frame Plating	0.0006	Nickel	7440-02-0	95.120	0.0004	0.0004
				Gold	7440-57-5	0.780	0.000003	
				Palladium	7440-05-3	4.100	0.00002	
		Semiconductor	0.003	Silicon	7440-21-3	100.000	0.002	0.002
		Semiconductor 2	0.0005	Silicon	7440-21-3	100.000	0.0004	0.0004
		Semiconductor 3	0.0005	Silicon	7440-21-3	100.000	0.0004	0.0004
		Mold Compound	0.21	Silicon Dioxide	60676-86-0	89.500	0.13	0.14
				Chlorine	7782-50-5	0.002	0.000003	
				Carbon Black	1333-86-4	0.500	0.0007	
				Epoxy	85954-11-6	9.998	0.01	
17	Diode 10V 300MW SO	Die	0.0005	Silicon	7440-21-3	100.000	0.0003	0.0003
		Lead Frame	0.0009	Nickel	7440-02-0	36.300	0.0002	0.001
				Iron	7439-89-6	50.200	0.0003	
				Copper	7440-50-8	13.500	0.0001	
		Mold Compound	0.003	Boron zinc hydroxide oxide	138265-88-0	3.000	0.0001	0.002

MATERIAL DECLARATION SHEET



				Zinc Monoxide	1314-13-2	0.500	0.00001	
				2,4,6-triamino-s-triazincompd.withs-triazine-triol	37640-57-6	3.000	0.0001	
				Silica Amorphous	7631-86-9	80.000	0.002	
				Carbon Black	1333-86-4	1.000	0.00002	
				Ortho-Cresol Novolac Resin	29690-82-2	8.000	0.0002	
				Phenolic Resin	9003-35-4	4.500	0.0001	
		Plating	0.0001	Tin	7440-31-5	100.000	0.0001	0.0001
18	Capacitor 16pF 50V NPO x2	Wire Bond - Cu	0.00001	Copper	7440-50-8	100.000	0.0001	0.00001
		Ceramic Substrate	0.009	Calcium zirconium oxide	12013-47-7	100.000	0.006	0.006
		Inner Electrode	0.0005	Nickel	7440-02-0	100.000	0.0004	0.0004
		Termination Electrode	0.001	Copper	7440-50-8	100.000	0.001	0.001
		Under plating	0.00008	Nickel	7440-02-0	100.000	0.0001	0.0001
19	Microchip IC	Mold Compound	0.0013	Tin	7440-31-5	100.000	0.0002	0.0002
				Silica	60676-86-0	86.910	0.001	0.001
				Epoxy Resin	Trade Secret	7.670	0.0001	
				Phenolic Resin	Trade Secret	5.110	0.00005	
		Lead Frame	0.00168	Carbon Black	1333-86-4	0.310	0.000003	0.001
				Copper	7440-50-8	95.540	0.001	
				Iron	7439-89-6	2.350	0.00003	
				Silver	7440-22-4	1.900	0.00002	
				Zinc	7440-66-6	0.130	0.000002	
				Phosphorus	7723-14-0	0.080	0.000001	
		Die Attach	0.00012	Silver	7440-22-4	75.000	0.0001	0.0001
				2,6-diglycidylphenyl glycidyl ether	13561-08-5	14.000	0.00001	
				Bisphenol A epoxy resin	54208-63-8	7.500	0.00001	
				4-methyl-2-phenylimidazole	827-43-0	3.500	0.000003	

MATERIAL DECLARATION SHEET



		Chip (Die)	0.0012	Doped Silicon	7440-21-3	100.000	0.001	0.001
		Wire Bond	0.00003	Copper	7440-50-8	98.250	0.00002	0.00002
				Palladium	7440-05-3	1.750	0.0000004	
		Plating	0.0002	Tin	7440-31-5	100.000	0.0001	0.0001
20	Resistor 10K OHM 1% 1/10W x2	Ceramic Substrate	0.0033	Aluminum Oxide	1344-28-1	96.000	0.002	0.002
				Silicon Dioxide	14808-60-7	3.000	0.0001	
				Magnesium Oxide	1309-48-4	1.000	0.00002	
		Inner termination - top side	0.0002	Silver	7440-22-4	70.000	0.0001	0.0001
				Palladium	7440-05-3	0.400	0.000001	
				Ethyl cellulose	9004-57-3	8.000	0.00001	
				Butyl carbitol	112-34-5	21.600	0.00003	
		Inner termination - bottom side	0.0001	Silver	7440-22-4	61.000	0.00004	0.0001
				Butyl digol	112-34-5	22.000	0.00002	
				Terpineol	8000-41-7	17.000	0.00001	
		Resistive element	0.00005	Silver	7440-22-4	25.000	0.00001	0.00004
				Palladium	7440-05-3	5.000	0.000002	
				Ruthenium oxide	12036-10-1	35.000	0.00001	
				Lead	7439-92-1	11.66	0.000004	
				Boron	7440-42-8	11.67	0.000004	
				Silica	10279-57-9	11.67	0.000004	
		Pre-coat	0.00004	Lead bisilicate	65997-18-4	75.000	0.00002	0.00003
				Terpineol	8000-41-7	25.000	0.00001	
		Over-coat	0.00004	Polydimethylsiloxane	9016-00-6	100.000	0.00003	0.00003
		Marking	0.000008	Bisphenol A diglycidyl ether homopolymer	25085-99-8	50.000	0.000003	0.00001
				Barium Sulfate	7727-43-7	15.000	0.000001	
				Titanium dioxide	13463-67-7	30.000	0.000002	
				Diethylene glycol monoethyl ether acetate	112-15-2	5.000	0.0000003	
		Middle Termination	0.000099	Nickel	7440-02-0	100.000	0.0001	0.0001
		Side termination	0.000004	Nickel	7440-02-0	80.000	0.000002	0.000003

MATERIAL DECLARATION SHEET



				Chromium	7440-47-3	20.000	0.000001	
		Outer termination	0.000004	Tin	7440-31-5	100.000	0.000003	0.000003
21	Resistor 2.2K OHM 1% 1/10W x2	Ceramic Substrate	0.0033	Aluminum Oxide	1344-28-1	96.000	0.002	0.002
				Silicon Dioxide	14808-60-7	3.000	0.0001	
				Magnesium Oxide	1309-48-4	1.000	0.00002	
		Inner termination - top side	0.00019	Silver	7440-22-4	70.000	0.0001	0.0001
				Palladium	7440-05-3	0.400	0.000001	
				Ethyl cellulose	9004-57-3	8.000	0.00001	
				Butyl carbitol	112-34-5	21.600	0.00003	
		Inner termination - bottom side	0.0001	Silver	7440-22-4	61.000	0.00004	0.0001
				Butyl digol	112-34-5	22.000	0.00002	
				Terpineol	8000-41-7	17.000	0.00001	
		Resistive element	0.00005	Silver	7440-22-4	25.000	0.00001	0.00004
				Palladium	7440-05-3	5.000	0.000002	
				Ruthenium oxide	12036-10-1	35.000	0.00001	
				Lead	7439-92-1	11.66	0.000004	
				Boron	7440-42-8	11.67	0.000004	
				Silica	10279-57-9	11.67	0.000004	
		Pre-coat	0.00004	Lead bisilicate	65997-18-4	75.000	0.00002	0.00003
				Terpineol	8000-41-7	25.000	0.00001	
		Over-coat	0.00004	Polydimethylsiloxane	9016-00-6	100.000	0.00003	0.00003
		Marking	0.000008	Bisphenol A diglycidyl ether homopolymer	25085-99-8	50.000	0.000003	0.00001
				Barium Sulfate	7727-43-7	15.000	0.000001	
				Titanium dioxide	13463-67-7	30.000	0.000002	
				Diethylene glycol monoethyl ether acetate	112-15-2	5.000	0.0000003	
		Middle Termination	0.000099	Nickel	7440-02-0	100.000	0.0001	0.0001
		Side termination	0.000004	Nickel	7440-02-0	80.000	0.000002	0.000003

MATERIAL DECLARATION SHEET



				Chromium	7440-47-3	20.000	0.000001	
		Outer termination	0.000004	Tin	7440-31-5	100.000	0.000003	0.000003
22	Transformer Driver IC	Die Attach Adhesive	0.0002	Silver	7440-22-4	80.000	0.0001	0.0001
				Epoxy	85954-11-6	20.000	0.00002	
		Lead Frame	0.006	Copper	7440-50-8	97.443	0.004	0.004
				Iron	7439-89-6	2.350	0.0001	
				Phosphorus	7723-14-0	0.083	0.000003	
				Zinc	7440-66-6	0.125	0.00000	
				Gold	7440-57-5	100.000	0.0001	
		Bond Wire	0.00009	Nickel	7440-02-0	95.240	0.0000003	0.0000003
		Lead Frame Plating	0.0000004	Gold	7440-57-5	0.760	0.000000002	
				Palladium	7440-05-3	4.000	0.00000001	
		Mold Compound	0.009	Fused Silica	60676-86-0	86.000	0.005	0.01
				Carbon Black	1333-86-4	0.500	0.00003	
				Epoxy	85954-11-6	13.500	0.001	
		Semiconductor Device	0.0003	Doped Silicon	7440-21-3	100.000	0.0002	0.0002
23	Resistor 1M OHM 5% 1/10W	Substrate	0.002	Aluminum Oxide	1344-28-1	96.600	0.0012	0.001
				Silicon Dioxide	14808-60-7	2.100	0.00003	
				Magnesium Oxide	1309-48-4	1.000	0.00001	
				Calcium Oxide	1305-78-8	0.300	0.000004	
		Top Terminal	0.00001	Silver	7440-22-4	96.880	0.00001	0.00001
				Palladium	7440-05-3	1.310	0.0000001	
				Lead Oxide	1317-16-8	0.900	0.0000001	
				Cupric Oxide	1317-38-0	0.600	0.0000001	
				Silicon Dioxide	7631-86-9	0.310	0.00000003	
		Bottom Terminal	0.00002	Silver	7440-22-4	97.490	0.00001	0.00001
				Lead Oxide	1317-16-8	1.500	0.0000002	
				Silicon Dioxide	7631-86-9	1.010	0.0000001	
		Resistive element	0.00001	Lead Oxide	1317-16-8	44.000	0.000003	0.00001
				Ruthenium oxide	12036-10-1	38.200	0.000002	

MATERIAL DECLARATION SHEET



				Boron oxide	1303-86-2	15.000	0.000001	
				Antimony compounds	Propietary	1.880	0.0000001	
				Manganese Dioxide	1313-13-9	0.920	0.0000001	
		First Protective Coating	0.00001	Lead Oxide	1317-16-8	54.990	0.00001	0.00001
				Silicon Dioxide	7631-86-9	25.600	0.000003	
				Boron Oxide	1303-86-2	12.900	0.000001	
				Zinc Oxide	1314-13-2	4.205	0.0000004	
				Chromium Oxide	1308-38-9	2.305	0.0000002	
		Second Protective Coating	0.00002	poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	69.000	0.000007	0.00001
				Silicon Dioxide	7631-86-9	23.000	0.000002	
				Carbon Black	1333-86-4	8.000	0.000001	
		Marking	0.000002	poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	61.000	0.000001	0.000001
				Silica gel	7631-86-9	30.500	0.0000004	
				Titanium dioxide	13463-67-7	8.500	0.0000001	
		Side Terminal	0.00008	Bisphenol A diglycidyl ethe	25068-38-6	45.000	0.00003	0.0001
				Silver	7440-22-4	45.000	0.00003	
				Carbon Black	1333-86-4	10.000	0.00001	
		Middle Terminal	0.0001	Nickel	7440-02-0	100.000	0.0001	0.0001
		Outer Terminal	0.00009	Tin	7440-31-5	100.000	0.0001	0.0001
24	Capacitor 2.2uF 100V X7	Dielectric	0.04	Barium titanate(IV)	12047-27-7	96.440	0.024	0.02
				Terbium(III,IV) oxide	12037-01-3	2.030	0.001	
				Others, not to declare	Propietary	1.530	0.0004	
		Inner Electrode	0.007	Nickel	7440-02-0	100.000	0.005	0.00
		Terminal Electrode	0.003	Copper	7440-50-8	100.000	0.002	0.002
		Electro-plating	0.0005	Nickel	7440-02-0	51.000	0.0002	0.0004
				Tin	7440-31-5	49.000	0.0002	
25	Resistor 0 OHM Jumper	Substrate	0.002	Aluminum Oxide	1344-28-1	96.000	0.001	0.001
				Crystalline silica, Quartz	14808-60-7	3.000	0.00004	
				Magnesium Oxide	1309-48-4	0.800	0.00001	

MATERIAL DECLARATION SHEET



			Others, not to declare	Propietary	0.200	0.000003	
	Inner Electrode (Top)	0.00005	Silver	7440-22-4	91.500	0.00003	0.00003
			Palladium	7440-05-3	2.500	0.000001	
			Lead Monoxide	1317-36-8	2.000	0.000001	
			Boric anhydride	1303-86-2	1.000	0.0000003	
			Crystalline silica, Quartz	14808-60-7	2.000	0.000001	
			Others, not to declare	Propietary	1.000	0.0000003	
	Inner Electrode (Bottom)	0.00003	Silver	7440-22-4	92.000	0.00002	0.00002
			Lead Monoxide	1317-36-8	3.000	0.000001	
			Boric anhydride	1303-86-2	2.000	0.0000005	
			Crystalline silica, Quartz	14808-60-7	2.000	0.0000005	
			Others, not to declare	Propietary	1.000	0.0000002	
	Inner Electrode (Side)	0.000001	Nickel	7440-02-0	50.000	0.0000003	0.000001
			Chromium	7440-47-3	50.000	0.0000003	
	Resistive film	0.00002	Silver	7440-22-4	92.000	0.00001	0.00001
			Lead Monoxide	1317-36-8	3.000	0.0000003	
			Boric anhydride	1303-86-2	2.000	0.0000002	
			Crystalline silica, Quartz	14808-60-7	2.000	0.0000002	
			Others, not to declare	Propietary	1.000	0.0000001	
	Inner Protective Coat	0.00001	Lead Monoxide	1317-36-8	49.000	0.000004	0.00001
			Boric anhydride	1303-86-2	19.500	0.000002	
			Crystalline silica, Quartz	14808-60-7	29.500	0.000003	
			Others, not to declare	Propietary	2.000	0.0000002	
	Outer Protective Coat	0.00003	Epoxy Resin	129915-35-1	59.000	0.00001	0.00002
			Crystalline silica, Quartz	14808-60-7	7.000	0.000002	
			Copper(II) oxide	1317-38-0	8.800	0.000002	
			Chromium(III) oxide	1308-38-9	18.000	0.000004	
			Manganese(IV) oxide	1313-13-9	3.000	0.000001	
			Others, not to declare	Propietary	4.200	0.000001	
	Marking	0.000008	Epoxy Resin	129915-35-1	67.000	0.000004	0.00001

MATERIAL DECLARATION SHEET



				Crystalline silica, Quartz	14808-60-7	10.000	0.000001	
				Titanium(IV) oxide	13463-67-7	20.000	0.000001	
				Others, not to declare	Proprietary	3.000	0.0000002	
		Plating	0.00008	Nickel	7440-02-0	100.000	0.0001	0.0001
		Solder Plating	0.00007	Tin	7440-31-5	100.000	0.00005	0.00005
26	Resistor 10K OHM 0.1% 1/16W	Ceramic Substrate	0.00175	Aluminum Oxide	1344-28-1	96.000	0.001	0.001
				Silicon oxide	7631-86-9	3.000	0.00004	
				Magnesium Oxide	1309-48-4	1.000	0.00001	
		Inner termination layer	0.000044	Silver	7440-22-4	90.000	0.00003	0.00003
				Terpineol	8000-41-7	10.000	0.000003	
		Resistive element	0.0000119	Nickel	7440-02-0	55.000	0.000005	0.00001
				Chromium	7740-47-3	45.000	0.000004	
		Over-coat	0.000035	2,2,4-trimethyl-1,3-pentanediol monoisobutyrate	25265-77-4	45.000	0.00001	0.00002
				Carbon Black	1333-86-4	3.000	0.000001	
				Silicon Dioxide	60676-86-0	25.000	0.00001	
				Talc	14807-96-6	15.000	0.000004	
				Diethylene glycol monobutyl ether	112-34-5	12.000	0.000003	
		Marking	0.00001	Ethyl cellulose	9004-57-3	80.000	0.00001	0.00001
				Pigment	13463-67-7	20.000	0.000001	
		Side Termination layer	0.0000001	Nickel	7440-02-0	55.000	0.00000004	0.0000001
				Chromium	7440-47-3	45.000	0.00000003	
		Middle termination layer	0.000005	Nickel	7440-02-0	100.000	0.000003	0.000003
		Outer Termination layer	0.000009	Tin	7440-31-5	100.000	0.00001	0.00001
27	Screw x2	Stainless Steel 304	0.513	Carbon	7440-44-0	0.080	0.0003	0.36
				Manganese	7439-96-5	2.000	0.01	

MATERIAL DECLARATION SHEET



				Phosphorus	7723-14-0	0.045	0.0002	
				Sulfur	7704-34-9	0.030	0.0001	
				Silicon	7440-21-3	0.750	0.003	
				Chromium	7440-47-3	18.000	0.06	
				Nickel	7440-02-0	8.000	0.03	
				Iron	7439-89-6	71.095	0.25	
28	Top Housing	Resin	9.918	Polyphenylene Sulfide	26125-40-6	59.500	4.09	6.8707
				Glass Fiber	65997-17-3	40.000	2.75	
				Carbon Black	1333-86-4	0.500	0.03	
29	Bottom Housing	Resin	9.358	Polyphenylene Sulfide	26125-40-6	59.500	3.86	6.4827
				Glass Fiber	65997-17-3	40.000	2.59	
				Carbon Black	1333-86-4	0.500	0.03	
30	Shunt	Manganin	9.891	Copper	7440-50-8	86.000	5.89	6.85
				Manganese	7439-96-5	12.000	0.82	
				Nickel	7440-02-0	2.000	0.14	
		Plating	0.005	Nickel	7440-02-0	100.000	0.003	0.003
		Copper Alloy	98.655	Copper	7440-50-8	99.950	68.309	68.34
				Oxygen	7782-44-7	0.050	0.034	
31	Resistor SMD 3.3 OHM 5% 0.4W	Substrate	0.004	Aluminum Oxide	1344-28-1	96.900	0.003	0.003
				Silicon Dioxide	7631-86-9	2.100	0.00006	
				Magnesium Oxide	1309-48-4	1.000	0.00003	
		Electrode 1	0.00004	Silver	7440-22-4	80.000	0.00002	0.00003
				Glass	65997-18-4	10.400	0.000003	
				Lead Oxide	1317-36-8	3.200	0.000001	
				Bismuth Oxide	1304-76-3	4.000	0.000001	
				Copper Oxide	1317-39-1	2.400	0.000001	
		Electrode 2	0.00008	Silver	7440-22-4	94.480	0.0000	0.0001
				Glass	65997-18-4	4.740	0.000002	
				Lead Oxide	1317-36-8	0.530	0.0000003	
				Boron Oxide	1303-86-2	0.250	0.0000001	
		Under coat	0.00005	Glass	65997-18-4	29.900	0.00001	0.00004

MATERIAL DECLARATION SHEET



				Lead Oxide	1317-36-8	59.650	0.00002	
				Boron Oxide	1303-86-2	8.210	0.000003	
				Chrome (III) oxide	1308-38-9	2.240	0.000001	
		Over coat	0.00006	Epoxy Resin	Propietary	47.690	0.00002	0.00004
				Silicone dioxide	7631-86-9	48.820	0.00002	
				Manganese oxide	1313-13-9	1.010	0.0000004	
				Chrome (III) oxide	1308-38-9	2.480	0.000001	
		Marking	0.000004	Epoxy Resin	Propietary	36.100	0.000001	0.000003
				Silicone dioxide	7631-86-9	63.900	0.000002	
		Side electrode	0.0004	Silver	7440-22-4	83.220	0.0002	0.0003
				Glass	65997-18-4	6.400	0.00002	
				Epoxy Resin	Propietary	10.380	0.00003	
		Middle electrode	0.0002	Nickel	7440-02-0	100.000	0.0001	0.0001
		External electrode	0.0001	Tin	7440-31-5	100.000	0.0001	0.0001
32	Solder Preform x4	Tin-Silver	0.104	Tin	7440-31-5	96.500	0.070	0.072
				Silver	7440-22-4	3.500	0.003	
33	Adhesive	Silicone	0.8	Limestone	1317-65-3	90.000	0.499	0.554
				Trimethoxyvinylsilane	2768-02-7	5.000	0.028	
				3-(Trimethoxysilyl) propylamine	13822-56-5	4.000	0.022	
				Quartz (SiO2)	14808-60-7	1.000	0.006	
34	PCB Multilayer	Copper Alloy	5.4500	Copper	7440-50-8	100.000	3.775	3.775
		Conformal Coating	0.0039	Epoxy Resin	26265-08	45.000	0.001	0.003
				Glass Fiber	26265-08-7	45.000	0.001	
				Silicon dioxide	65997-17-3	10.000	0.0003	
35	Conformal coating	Coating Silica	0.7000	Dichlorodimethyl	68611-44-9	97.000	0.470	0.485
				Aminopropyltriethoxysilane	919-30-2	3.000	0.015	
36	Diode 80V 0.5A 17 x2	Die Doped Silicon	0.0004	Silicon	7440-21-3	100.000	0.0003	0.0003
		Lead Frame	0.0048	Iron	7439-89-6	57.650	0.002	0.003

MATERIAL DECLARATION SHEET



				Nickel	7440-02-0	41.000	0.001	
				Manganese	7439-96-5	0.600	0.00002	
				Chromium	7440-47-3	0.100	0.000003	
				Cobalt	7440-48-4	0.500	0.00002	
				Silicon	7440-21-3	0.150	0.000005	
		Lead Frame plating	0.0002	Silver	7440-22-4	100.000	0.0001	0.0001
		Wire Bonding	0.0001	Gold	7440-57-5	100.000	0.00007	0.00007
		Molding Compound	0.0132	Silicon Dioxide	7631-86-9	83.000	0.008	0.009
				Zinc Oxide	1314-13-2	1.000	0.00009	
				Phenol-formaldehyde polymer	9003-35-4	10.000	0.0009	
				Boron zinc hydroxide oxide	138265-88-0	5.000	0.0005	
				Carbon black	1333-86-4	1.000	0.00009	
		Die Attach Epoxy	0.0017	Silver	7440-22-4	75.000	0.0009	0.001
				Epoxy resin	Trade secret	25.000	0.0003	
		Tin Plating	0.0004	Tin	7440-31-5	100.000	0.0003	0.0003
37	Diode 24VWM 40VC SO	Encapsulation	0.0027	Silica, vitreous	60676-86-0	87.700	0.002	0.002
				Epoxy resin	Not applicable	5.000	0.0001	
				Epoxy cresol novolac	29690-82-2	2.000	0.00004	
				Phenol resin	Not applicable	5.000	0.0001	
				Carbon Black	1333-86-4	0.300	0.00001	
		Leadframe	0.0021	Copper	7440-50-8	94.560	0.001	0.001
				Iron	7439-89-6	2.230	0.00003	
				Zinc	7440-66-6	0.010	0.0000001	
				Phosphorus	7723-14-0	0.030	0.0000004	
				Silver	7440-22-4	3.170	0.00005	
		Chip	0.0004	Silicon	7440-21-3	93.740	0.0003	0.0003
				Aluminum	7429-90-5	3.050	0.00001	

MATERIAL DECLARATION SHEET



				Nickel	7440-02-0	3.080	0.00001	
				Gold	7440-57-5	0.130	0.0000004	
		Die Attach	0.0001	Silver	7440-22-4	75.000	0.00004	0.0001
				Epoxy	9003-36-5	25.000	0.00001	
		Bond wires	0.00004	Gold	7440-57-5	100.000	0.00003	0.00003
		Terminal Finish	0.0001	Tin	7440-31-5	100.000	0.00006	0.0001
38	Resistor SMD 2.26K OHM	Inner Electrode	0.0002	Nickel	7440-02-0	48.700	0.00008	0.0002
				Copper	7440-50-8	49.390	0.00008	
				Tin	7440-31-5	1.910	0.000003	
		Protective Film	0.0009	Silicon Dioxide	7631-86-9	66.000	0.0004	0.001
				Misc. not to declare	Propietary	34.000	0.0002	
		External Electrode	0.0002	Tin	7440-31-5	100.000	0.0001	0.0001
		Ceramic	0.0036	Aluminum Oxide	1344-28-1	99.500	0.0025	0.003
				Silicon Dioxide	14808-60-7	0.300	0.00001	
				Magnesium Oxide	1309-48-4	0.200	0.00001	
		Resistive element	0.000001	Nickel	7440-02-0	80.000	0.0000003	0.0000004
				Chromium	7440-47-3	20.000	0.0000001	
39	Resistor 1.2M OHM 0.1% x8	Inner Electrode	0.0019	Nickel	7440-02-0	48.700	0.0006316	0.0013
				Copper	7440-50-8	49.390	0.0006405	
				Tin	7440-31-5	1.910	0.0000248	
		Protective Film	0.0070	Silicon Dioxide	7631-86-9	66.000	0.0032	0.005
				Misc. not to declare	Propietary	34.000	0.0017	
		External Electrode	0.0012	Tin	7440-31-5	100.000	0.0008	0.0008
		Ceramic	0.03	Aluminum Oxide	1344-28-1	99.500	0.0199	0.020
				Silicon Dioxide	14808-60-7	0.300	0.0001	
				Magnesium Oxide	1309-48-4	0.200	0.00004	
		Resistive element	0.000005	Nickel	7440-02-0	80.000	0.0000027	0.0000033
				Chromium	7440-47-3	20.000	0.0000007	
		Marking	0.00012	Silicon Dioxide	7631-86-9	100.000	0.00008	0.00008

MATERIAL DECLARATION SHEET



40	Power Transformers	Header filled thermoplastics.	0.058	Aluminum hydroxide	21645-51-2	40.000	0.02	0.04
				Glass fiber	65997-17-3	30.000	0.01	
				Diallyl phthalate resin	25035-78-3	25.000	0.01	
				Antimonyoxide (Sb ₂ O ₃)	1309-64-4	4.500	0.002	
				Carbon black	1333-86-4	0.500	0.0002	
		Terminal copper alloys	0.0077	Copper	7440-50-8	93.450	0.0050	0.005
				Tin	7440-31-5	6.050	0.0003	
				Phosphorus	7723-14-0	0.350	0.00002	
				Zinc	7440-66-6	0.100	0.00001	
				Iron	7439-89-6	0.050	0.000003	
		Terminal Plating Special metals	0.0004	Nickel	7440-02-0	34.000	0.0001	0.0003
				Tin	7440-31-5	66.000	0.0002	
		Ceramics/glass	0.015	Ironoxide	1317-61-9	70.000	0.007	0.01
				Manganeseoxide	1317-35-7	17.000	0.002	
				Zincioxide	1314-13-2	13.000	0.001	
		Wire Copper	0.0036	Copper	7440-50-8	98.700	0.00	0.002
				Tin	7440-31-5	1.300	0.0000	
		Wire Lacquers	0.0003	Poly(tetrafluoroethylene-co-perfluoro(propylvinyl ether))	26655-00-5	100.000	0.0002	0.0002
		Solder	0.0042	Tin	7440-31-5	96.000	0.003	0.0029
				Silver	7440-22-4	4.000	0.0001	
		Core Coating	0.0002	Paracyclophane	1633-22-3	99.000	0.0001	0.0001
				Trade secret	N/A	1.000	0.000001	
		Wire Copper In cable harnesses	0.002	Copper	7440-50-8	100.000	0.001	0.001
		Wire Lacquers	0.0003	Polyurethane	9009-54-5	94.400	0.0002	0.0002
				Polyamide resin	70024-79-2	5.600	0.00001	
		Wire Copper Alloy	0.0014	Copper	7440-50-8	100.000	0.001	0.001
		Wire Tin Plating	0.00004	Tin	7440-31-5	100.000	0.00003	0.00003

MATERIAL DECLARATION SHEET



		Wire Isolation Lacquers	0.0015	polymer with tetrafluoroethene	26655-00-5	99.580	0.001	0.001
				C.I. Pigment Blue 28	1345-16-0	0.180	0.000002	
				Titanium oxide (TiO ₂)	13463-67-7	0.180	0.000002	
				C.I. Pigment Green 50	68186-85-6	0.060	0.000001	
		Wire Isolation Copper Alloy	0.0009	Copper	7440-50-8	97.950	0.0006	0.001
				Tin	7440-31-5	2.050	0.00001	
		Adhesive Sealants	0.0024	Bisphenol A Di glycidyl ether resin	25068-38-6	50.000	0.0008	0.002
				Talc	14807-96-6	14.000	0.0002	
				Crystalline silica	14808-60-7	10.000	0.0002	
				Titanium oxide (TiO ₂)	13463-67-7	1.000	0.00002	
				Limestone	1317-65-3	25.000	0.0004	
		Wire Copper amounts in cable harnesses	0.0021	Copper	7440-50-8	100.000	0.0014	0.001
		Wire Lacquers	0.0001	Polyurethane	9009-54-5	100.000	0.0001	0.0001
41	Mosfets P-CH	Bond Wire	0.00002	Copper	7440-50-8	100.000	0.00001	0.00001
		Die	0.00099	Aluminum	7429-90-5	1.010	0.00001	0.001
				Doped Silicon	7440-21-3	98.990	0.0007	
		Die Attach Adhesive	0.00003	Proprietary Resin	129915-35-1	33.330	0.00001	0.00002
				Silver	7440-22-4	66.670	0.00001	
		Lead frame	0.00402	Copper	7440-50-8	99.480	0.002771	0.003
				Iron	7439-89-6	0.250	0.000007	
				Phosphorus	7723-14-0	0.020	0.000001	
				Zinc	7440-66-6	0.250	0.000007	
		Mold Compound	0.006	Epoxy Resin	29690-82-2	8.000	0.0003	0.004
				Fused Silica	60676-86-0	76.870	0.003	
				Metal Hydroxide	21645-51-2	8.000	0.0003	
				Phenol Resin	9003-35-4	7.130	0.0003	
		Solder Plating	0.0001	Tin	7440-31-5	100.000	0.0001	0.0001

MATERIAL DECLARATION SHEET



42	Thermistors NTC 10KOHM	Ceramic element	0.0040	Manganese oxide	1317-35-7	50.000	0.001	0.003
				Nickel monoxide	1313-99-1	25.000	0.001	
				Iron(III) oxide	1309-37-1	15.000	0.0004	
				Misc. not to declare	Trade secret	10.000	0.0003	
		Nickel plating	0.00003	Nickel	7440-02-0	100.000	0.00002	0.00002
		Tin Plating	0.0001	Tin	7440-31-5	100.000	0.0001	0.0001
		Inner electrode	0.0002	Silver	7440-22-4	70.000	0.0001	0.0001
				Palladium	7440-05-3	30.000	0.00003	
		Outer electrode	0.0004	Copper	7440-50-8	89.000	0.0003	0.0003
				Silicon dioxide	7631-86-9	8.000	0.00002	
				Diboron trioxid	1303-86-2	3.000	0.00001	
43	Crystal 16.0000MHZ 10PF	Package - Ceramics	0.011648	Aluminum oxide	1344-28-1	90.00	0.0073	0.008
				Silicon oxide	7631-86-9	6.00	0.0005	
				Chromium oxide	1308-38-9	2.00	0.0002	
				Molybdenum	7439-98-7	2.00	0.0002	
		Package - Kovar	0.0003	Iron	7439-89-6	53.00	0.0001	0.0002
				Nickel	7440-02-0	29.00	0.0001	
				Cobalt	7440-48-4	18.00	0.00003	
		Package - Plate	0.0004	Gold	7440-57-5	19.00	0.00005	0.0003
				Nickel	7440-02-0	81.00	0.00022	
		Package- Metallizing	0.0001	Tungsten	7440-33-7	100.00	0.00009	0.0001
		Package- Solder	0.0004	Silver	7440-22-4	71.00	0.00019	0.0003
				Copper	7440-50-8	29.00	0.00008	
		Lid - Kovar	0.00319	Iron	7439-89-6	53.24	0.00118	0.002
				Nickel	7440-02-0	29.00	0.00064	
				Cobalt	7440-48-4	17.00	0.00038	
				Manganese	7439-96-5	0.50	0.00001	
				Silicon	7440-21-3	0.20	0.000004	
				Carbon	7440-44-0	0.06	0.000001	
		Lid - Plating	0.00029	Nickel	7440-02-0	100.00	0.0002	0.0002

MATERIAL DECLARATION SHEET



		Quartz	0.00063	Silicon dioxide	14808-60-7	100.00	0.0004	0.0004
		Electrode Cr target	0.000002	Chromium	7440-47-3	100.00	0.000001	0.000001
		Electrode Ag target	0.000037	Silver	7440-22-4	100.00	0.000026	0.00003
		Conductive Adhesive	0.0000346	Silver	7440-22-4	77.08	0.000018	0.00002
Silica	7631-86-9			8.33	0.000002			
Silicone Resin	68554-70-1			14.59	0.000003			
44	Silicone	SS-5600 Part A	0.8	Dimethyl Silicone Resin	63148-62-9	44.03	0.244013	0.55420
				3-Aminopropyltrimethoxysilane	13822-56-5	5.25	0.029095	
				Hexamethyldisiloxane	107-46-0	2.40	0.013301	
				Quartz	14808-60-7	35.03	0.194135	
				Silicon Dioxide	7631-86-9	13.29	0.073653	
45	Silicone	SS-5600 Part B	0.8	Dimethyl Silicone Resin	63148-62-9	47.45	0.262966	0.55420
				Quartz	14808-60-7	35.56	0.197072	
				Silicon Dioxide	7631-86-9	16.93	0.093826	
				Dibutyltin dilaurate	77-58-7	0.06	0.000333	
46	Solder Paste	Solder Paste, 96.5 Sn/3.5Ag	0.003	Tin	7440-31-5	86	0.001787	0.00208
				Silver	7440-22-4	5	0.000104	
				Rosin	65997-06-0	5	0.000104	
				2-ethylhexane-1,3-diol	94-96-2	3	0.000062	
				Misc, not to declare	--	1	0.000021	
47	Solder	Lead Free Solder	0.02	Tin	7440-31-5	88	0.0122	0.01385
				Silver	7440-22-4	7	0.0010	
				Copper	7440-50-8	5	0.0007	
		Total Weight	144.353					

MATERIAL DECLARATION SHEET



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